



NOTES:

1. MATERIAL:

1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.

1.2 CONTACT: COPPER ALLOY

1.3 SHELL: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

50 μ m MIN. NICKEL UNDERPLATING OVERALL.1:1~3 μ m GOLD ON CONTACT FOR LEAD FREET:10 μ m GOLD ON CONTACT FOR LEAD FREED:30 μ m GOLD ON CONTACT FOR LEAD FREEB:5 μ m GOLD ON CONTACT FOR LEAD FREEC:15 μ m GOLD ON CONTACT FOR LEAD FREE

2.2 SHELL:

50 μ m MIN. NICKEL UNDERPLATING OVERALL.50~100 μ m MATT TIN PLATING ON SOLDER

3. SPEC. PLS. REFER TO PS-50398-XXXX

4. PACKAGE PLS. REFER TO 50406-XXXX-TRP/50406-XXXX-00-TRP

50406-XXXX-02-TRP

5. MATING CONNECTOR P/N:50407

6. PART NUMBER

50406-XXX	X	X-XXX	XXX	PACKING
030.30Pin			001	50406-XXXX-00(WITH MYLAR)
			W01	50406-XXXX-02

CONTACT PLATING

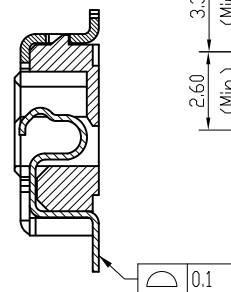
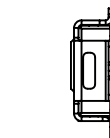
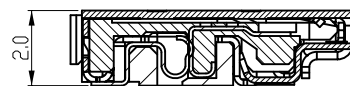
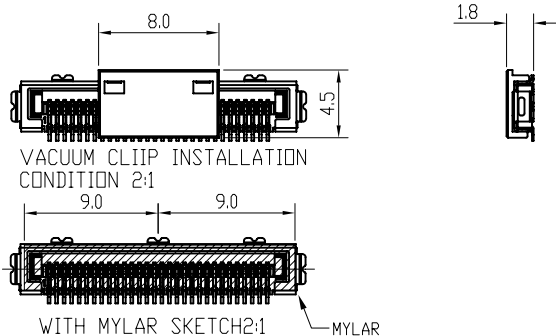
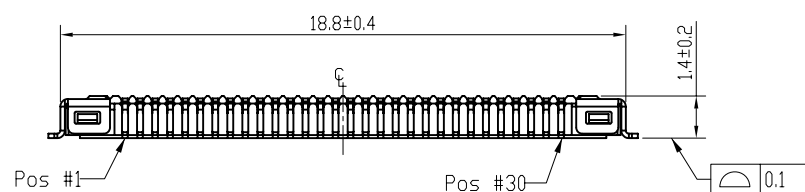
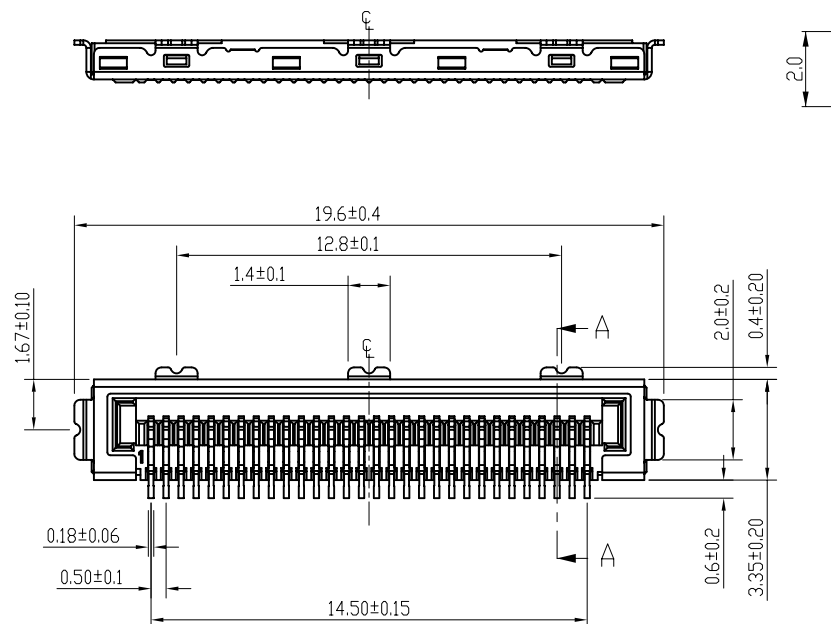
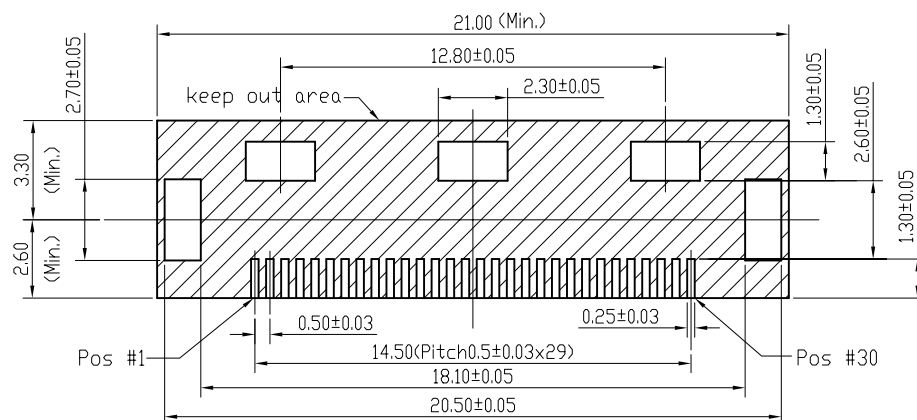
1:1~3 μ m GOLD ON CONTACT FOR LEAD FREET:10 μ m GOLD ON CONTACT FOR LEAD FREED:30 μ m GOLD ON CONTACT FOR LEAD FREEB:5 μ m GOLD ON CONTACT FOR LEAD FREEC:15 μ m GOLD ON CONTACT FOR LEAD FREE


PACKING

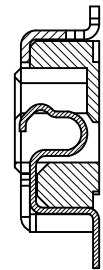
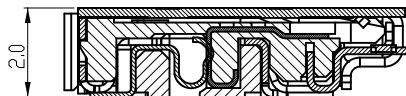
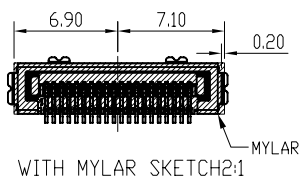
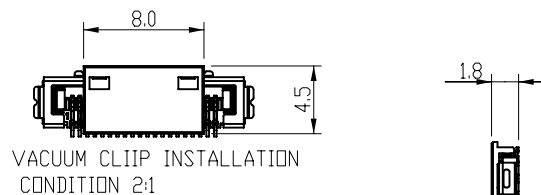
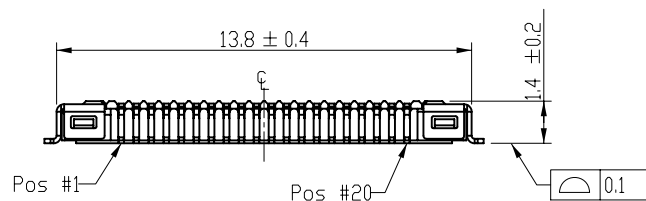
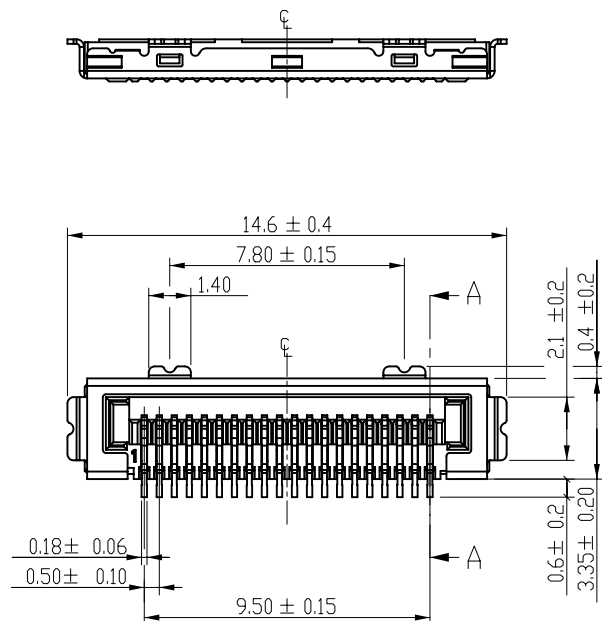
1.TUBE

7.TAPE REEL WITH COVER

4.TAPE REEL WITH MYLAR

Section A-A
Scale 8:1

一般公差 TOLERANCES X. ±0.5 XX ±0.15 .X ±0.25 .XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.					
檢驗尺寸標示 SYMBOLS ① ② INDICATE CLASSIFICATION DIMENSION ① MARK IS CRITICAL DIM. ② MARK IS MAJOR DIM.	品名 (TITLE) 0.5mm LVDS CONN.		製圖 (DR) 14/03/08 XIUJIN				
	圖號 (DWG NO.) 50406-XXXX-XXX		審核 (CHKD) BRAVE				
			核准 (APPD) JERRY				
表面處理 (FINISH) _____		比例 (SCALE) 4:1	單位 (UNITS) mm		張數 (SHEET) 1 OF 3	SIZE A4	REV H



Section A-A
Scale 8:1

NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
- 1.2 CONTACT: COPPER ALLOY
- 1.3 SHELL: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

- 50u" MIN. NICKEL UNDERPLATING OVERALL.
- 1:1~3u" GOLD ON CONTACT FOR LEAD FREE
- T:10u" GOLD ON CONTACT FOR LEAD FREE
- D:30u" GOLD ON CONTACT FOR LEAD FREE
- B:5u" GOLD ON CONTACT FOR LEAD FREE
- C:15u" GOLD ON CONTACT FOR LEAD FREE

2.2 SHELL:

- 50u" MIN. NICKEL UNDERPLATING OVERALL.
- 50~100u" MATT TIN PLATING ON SOLDER

3. SPEC. PLS. REFER TO PS-50398-XXXX

4. PACKAGE PLS. REFER TO 50406-XXXX-TRP/50406-XXXX-02-TRP 50406-XXXX-04-TRP

5. MATING CONNECTOR P/N:50407

6. PART NUMBER

50406-XXX X X-XXX

020.20Pin

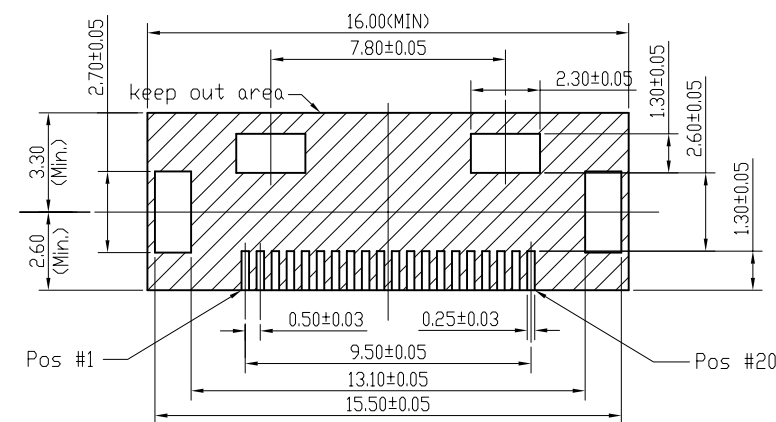
XXX	PACKING
001	50406-XXXXCR
W01	50406-XXXXCR-02
AT1	50406-XXXXCR-04

PACKING

- 1.TUBE
- 7.TAPE REEL WITH COVER
- 4.TAPE REEL WITH MYLAR

CONTACT PLATING

- 1:1~3u" GOLD ON CONTACT FOR LEAD FREE
- T:10u" GOLD ON CONTACT FOR LEAD FREE
- D:30u" GOLD ON CONTACT FOR LEAD FREE
- B:5u" GOLD ON CONTACT FOR LEAD FREE
- C:15u" GOLD ON CONTACT FOR LEAD FREE



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表面處理 (FINISH)		圖號 (DWG NO.) 50406-XXXX-XXX	核准 (APPD) JERRY	張數 (SHEET) 2 OF 3	SIZE A4
比例 (SCALE) 4:1		單位 (UNITS) mm	①	REV H	



NOTES:

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50~100u" MATT TIN PLATING ON SOLDER

3. SPEC. PLS. REFER TO PS-50398-XXXXX

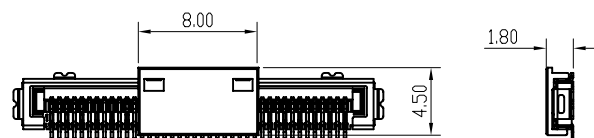
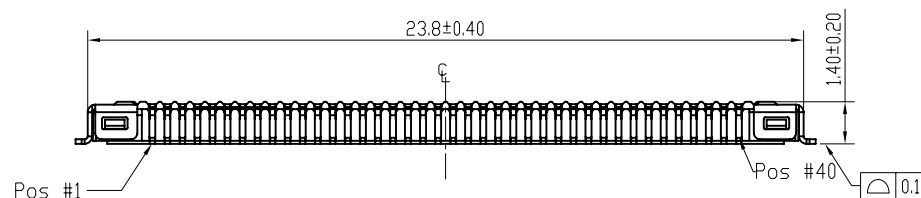
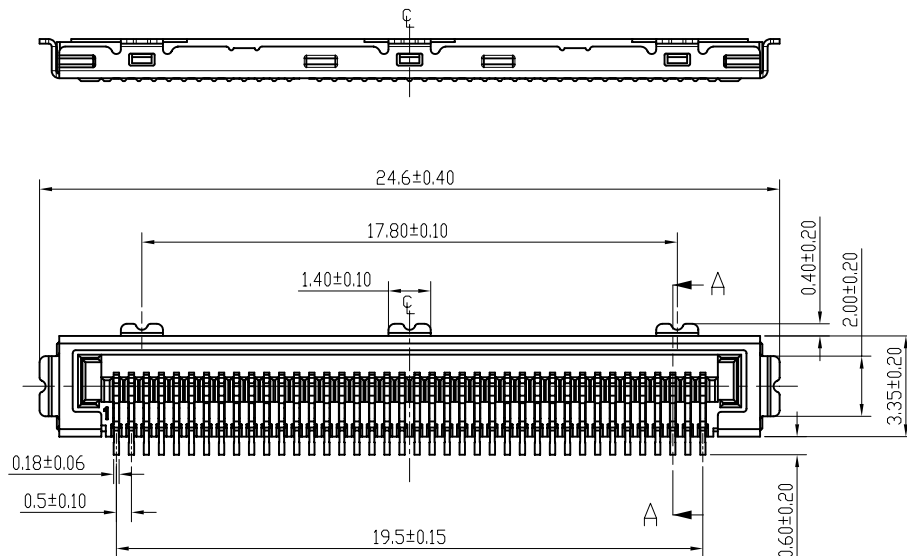
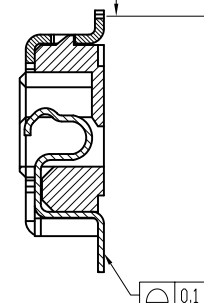
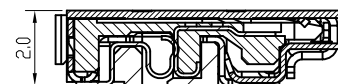
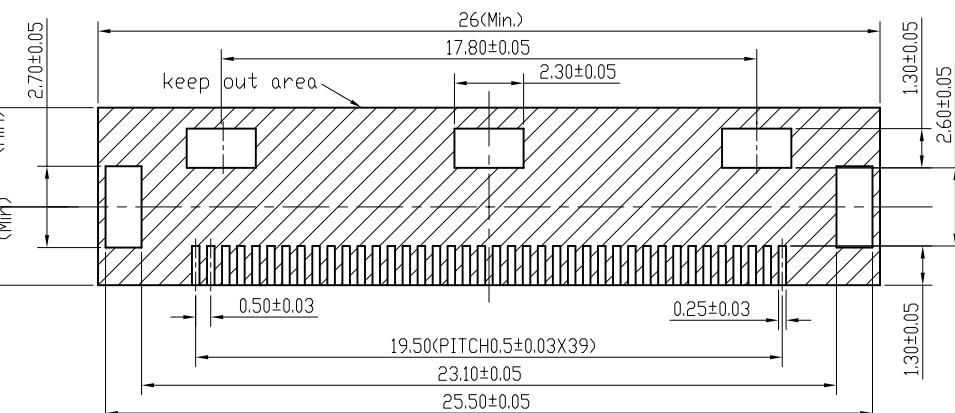
4. PACKAGE PLS. REFER TO 50406-XXXXX-TRP/50406-XXXXX-02-TRP

5. MATING CONNECTOR P/N:50407

6. PART NUMBER

50406-XXX X X-XXX

XXX	PACKING
001	50406-XXXXCR
W01	50406-XXXXCR-02

040:40Pin
PACKING
1.TUBE
7.TAPE REEL WITH COVER
4.TAPE REEL WITH MYLARCONTACT PLATING
1:1~3u" GOLD ON CONTACT FOR LEAD FREE
T:10u" GOLD ON CONTACT FOR LEAD FREE
D:30u" GOLD ON CONTACT FOR LEAD FREE
B:5u" GOLD ON CONTACT FOR LEAD FREE
C:15u" GOLD ON CONTACT FOR LEAD FREEVACUUM CLIP INSTALLATION
CONDITION 2:1SECTION B-B
SCALE 8:1

一般公差 TOLERANCES X. ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.			
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表面處理 (FINISH)		比例 (SCALE) 4:1	單位 (UNITS) mm	核准 (APPD) JERRY	張數 (SHEET) 3 OF 3
				SIZE A4	REV H